



VMDSEMI

VUPB003R075NA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
30V	7.5mΩ@10V	50A
	11.5mΩ@4.5V	

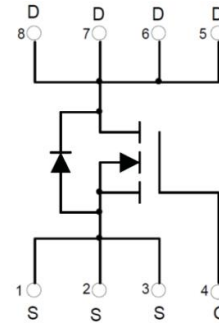
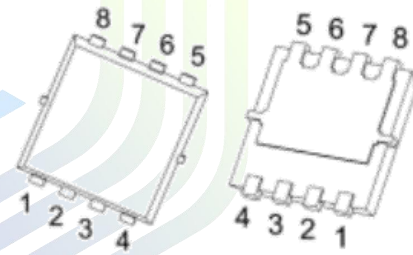


Figure 1 Symbol of VUPB003R075NA

Features

- Trench Technology Power MOSFET
- Low Gate Resistance
- Low $R_{DS(ON)}$
- 100% UIS Tested

Package Type



PDFN5X6-8L

Application

- Power Switch Application
- DC/DC Converters

Figure 2 Package Type of VUPB003R075NA

Ordering Information

Product Name	Package
VUPB003R075NA	PDFN5X6-8L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	50	A
Pulsed Drain Current ^{Note2}	I_{DM}	200	
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	126	mJ
Avalanche Current ^{Note3}	I_{AS}	23	A
Total Power Dissipation ^{Note5}	P_D	31	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		53		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		4		°C/W



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.6	3.0	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$		5.5	7.5	mΩ
		$V_{GS}=4.5V, I_D=10A$		7.8	11.5	
Forward Transconductance ^{Note4}	g_{FS}	$V_{DS}=5V, I_D=20A$		55		S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=15V$		1581		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		208		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		160		pF
Total Gate Charge	Q_g	$V_{DS}=15V$		30		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		4		
Gate-Drain Charge	Q_{gd}	$I_D=10A$		6		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		2.4		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V$		6.5		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		2		
Turn-off Delay Time	$t_{d(off)}$	$R_L=0.75\Omega$		17		
Turn-off Fall Time	t_f	$R_G=3\Omega$		3.5		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=10A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD}=25V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$ Starting $T_J=25^\circ C$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)}=150^\circ C$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$.

Typical Performance Characteristics

Figure 3: Transfer Characteristics

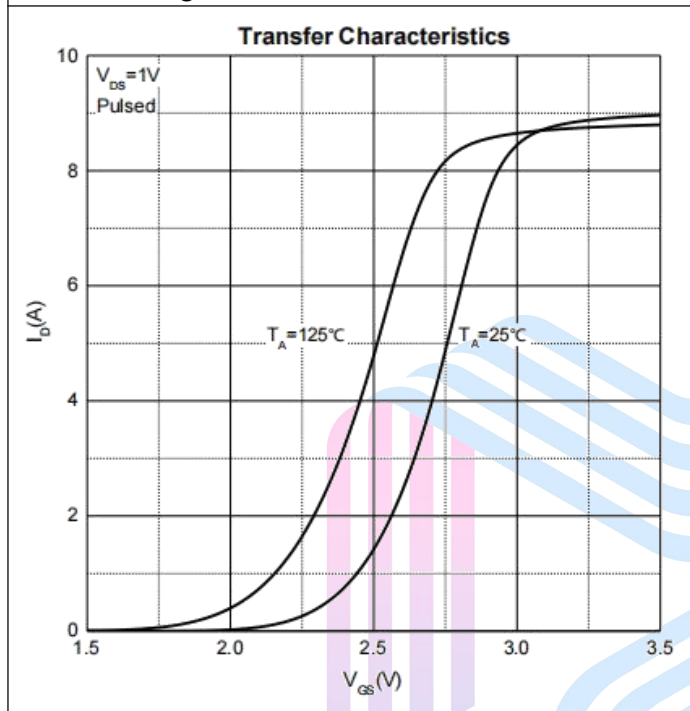


Figure 4: Output Characteristics

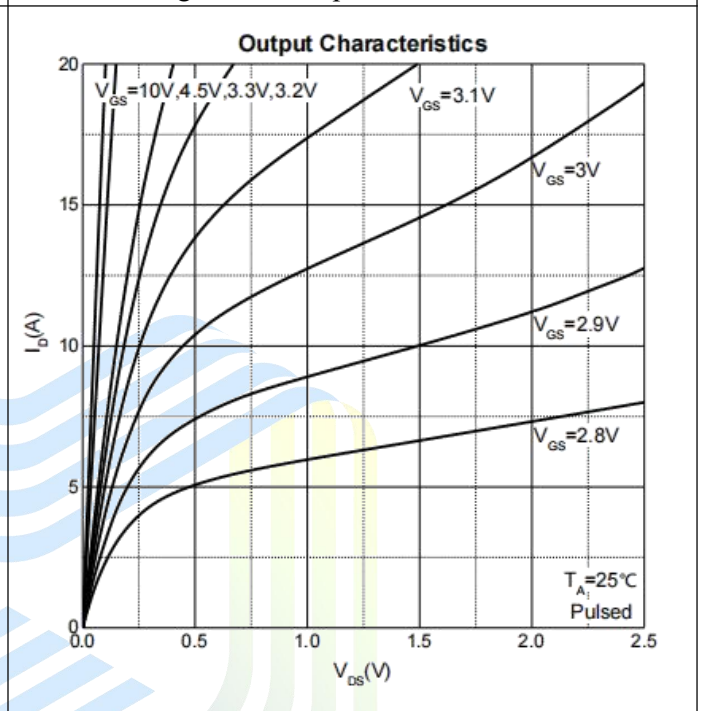


Figure 5: On-Resistance vs. Drain Current

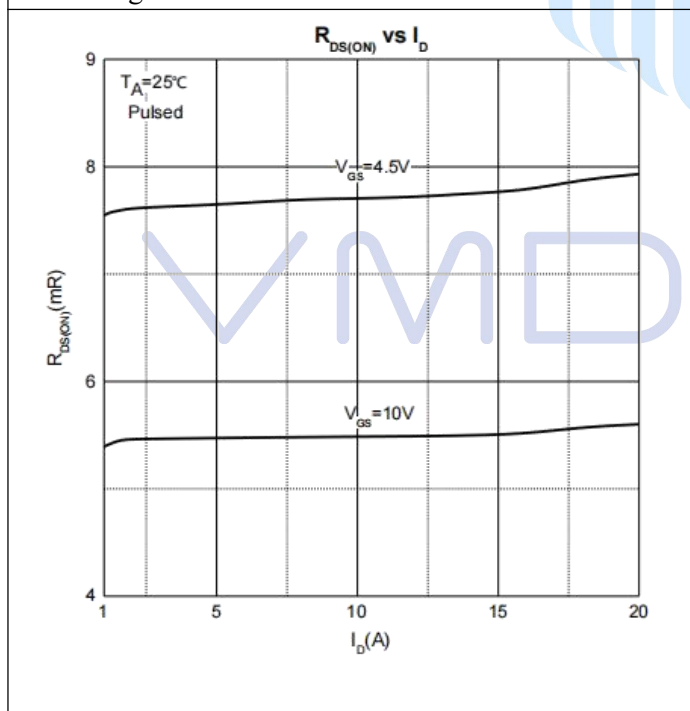


Figure 6: On-Resistance vs. Gate Voltage

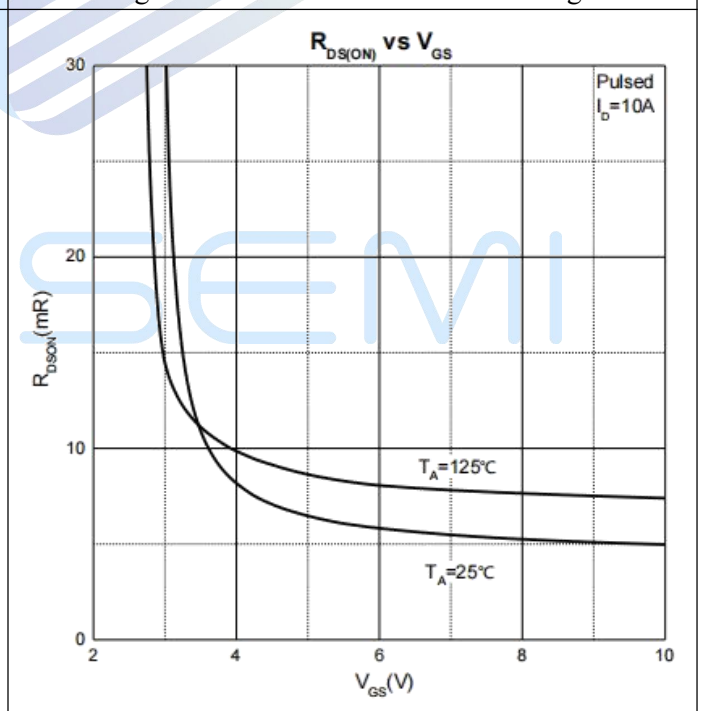


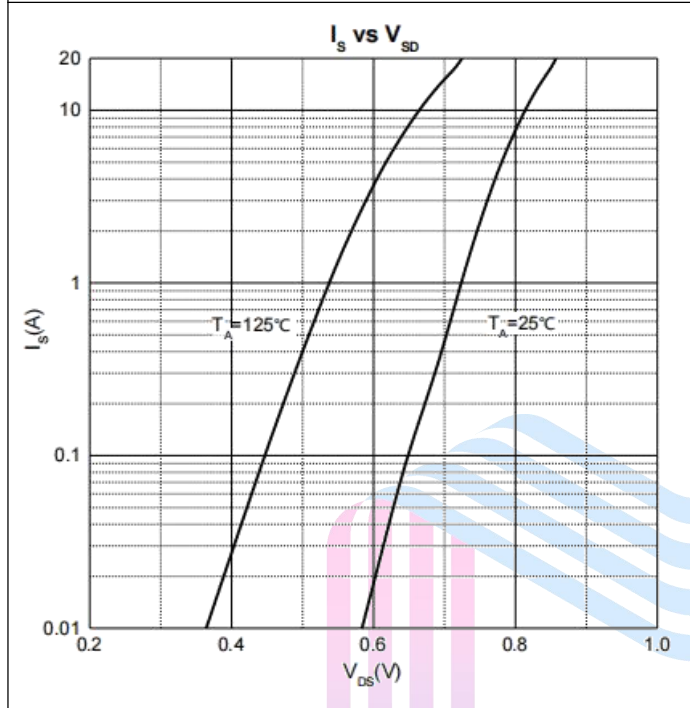
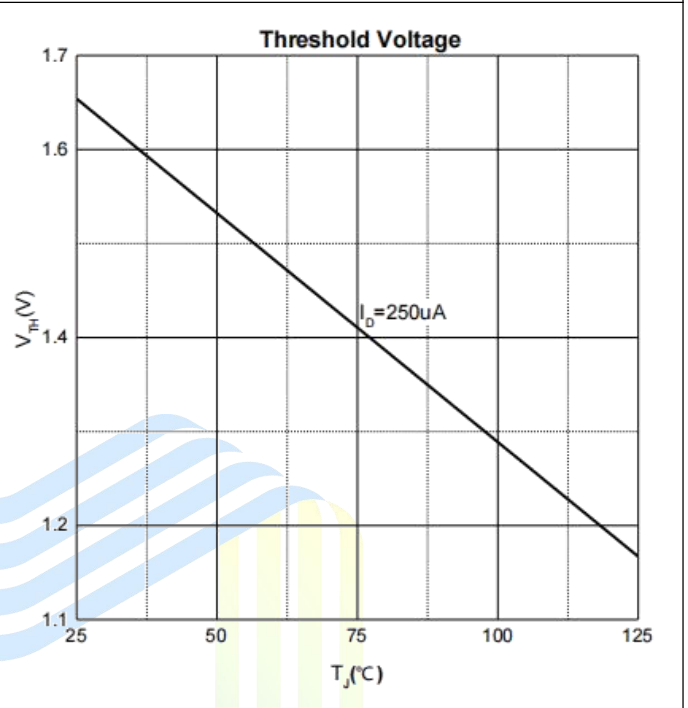
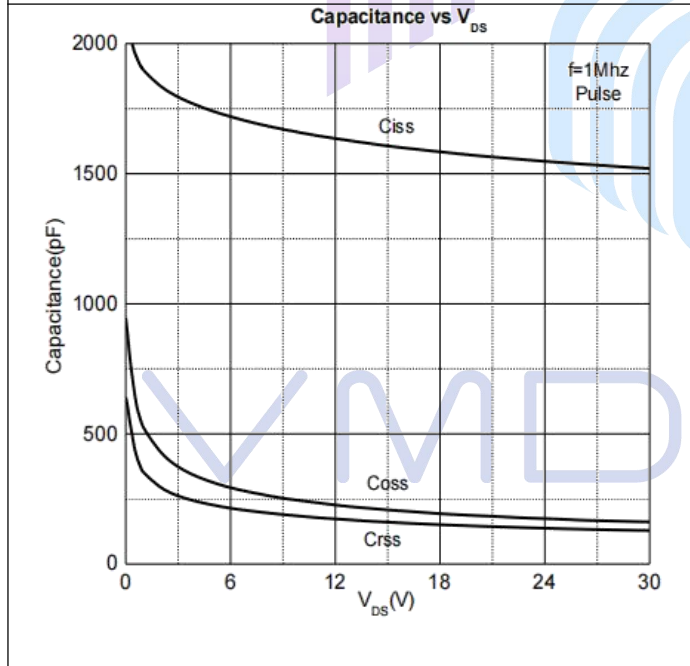
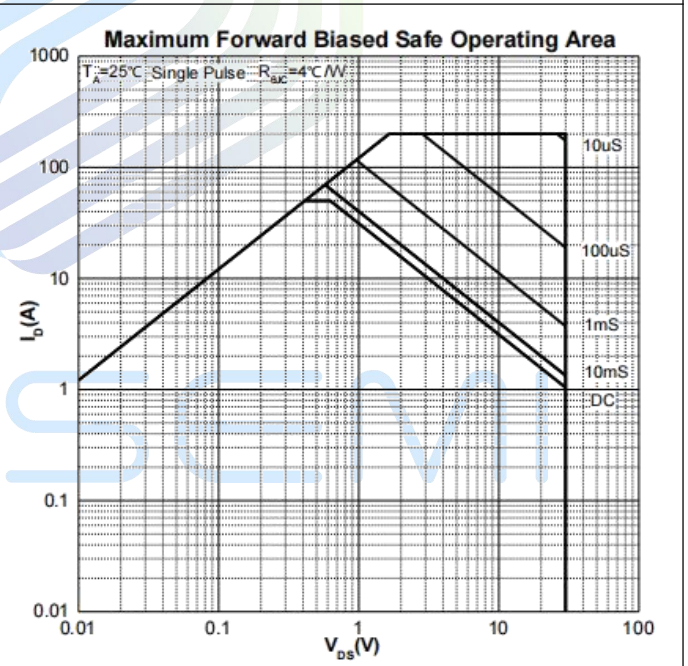
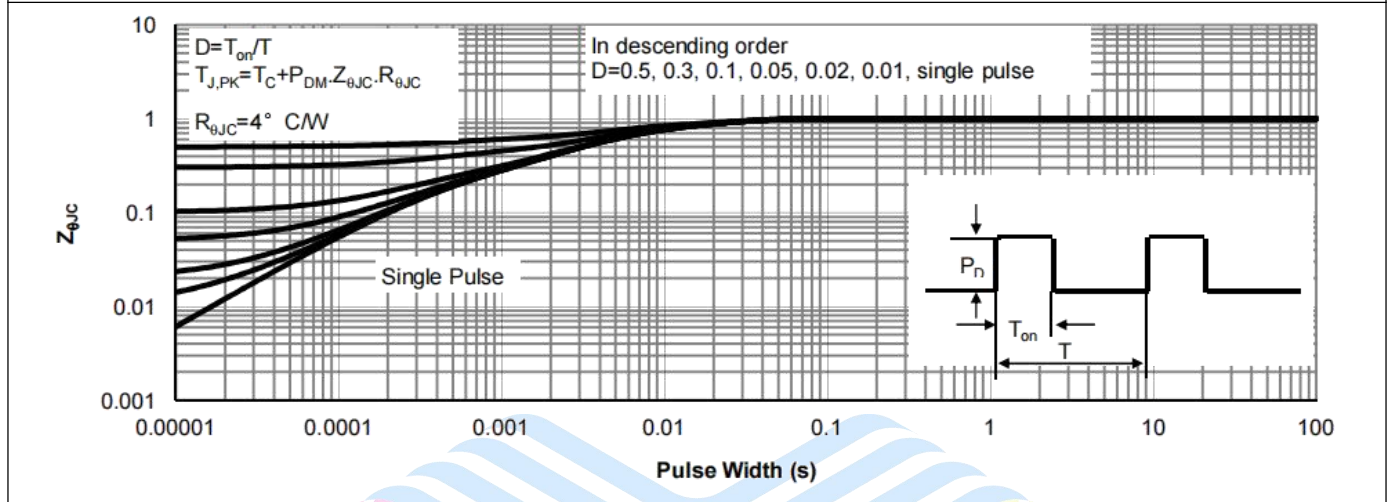
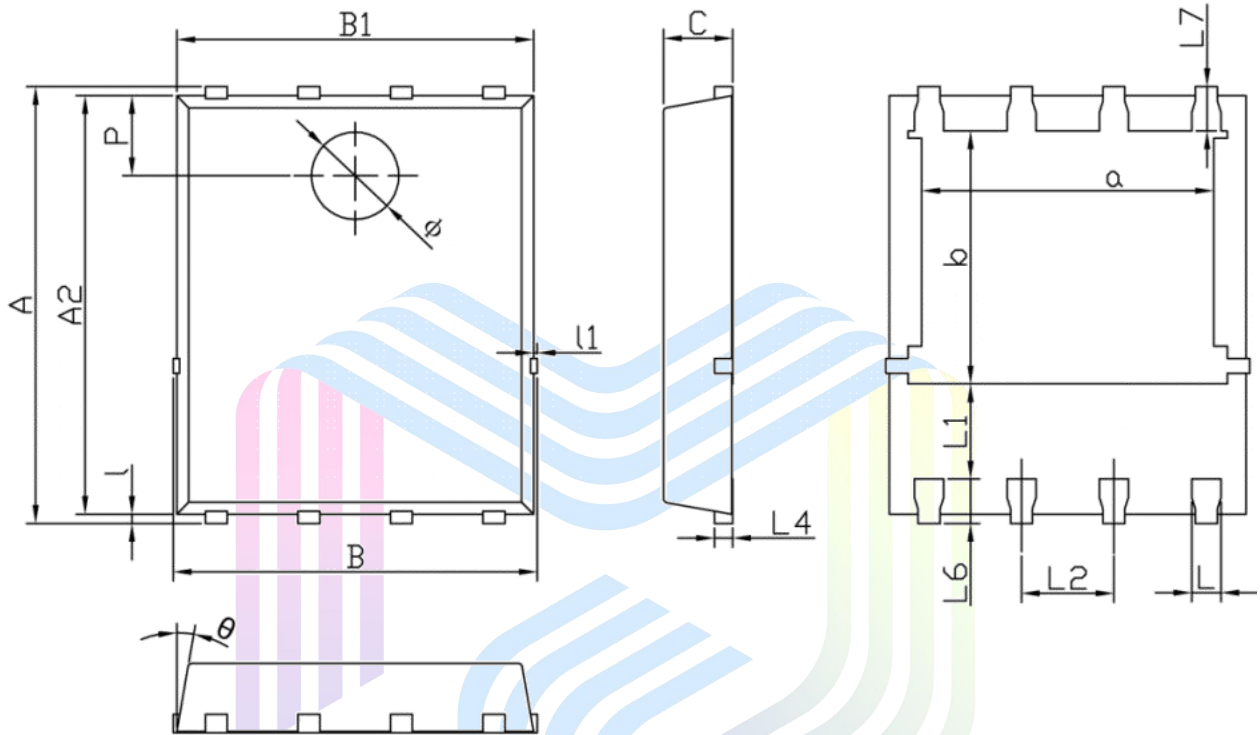
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance



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Mechanical Dimensions:
PDFN5X6-8L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	5.900	6.100	0.232	0.240
a	3.910	4.110	0.154	0.162
A2	5.700	5.800	0.224	0.228
B	4.900	5.100	0.193	0.201
b	3.370	3.570	0.133	0.141
B1	4.800	5.000	0.189	0.197
C	0.900	1.000	0.035	0.039
L	0.350	0.450	0.014	0.018
l	0.060	0.200	0.002	0.008
L1	1.100	-	0.043	-
l1	-	0.100	-	0.004
L2	1.170	1.370	0.046	0.054
L4	0.210	0.340	0.008	0.013
L6	0.510	0.710	0.020	0.028
L7	0.510	0.710	0.020	0.028
P	1.000	1.200	0.039	0.047
Φ	1.100	1.300	0.043	0.051
θ	8°	12°	8°	12°

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